

A Complete System Approach to NAND in Computing

Dean Klein

Micron Technology, Inc.



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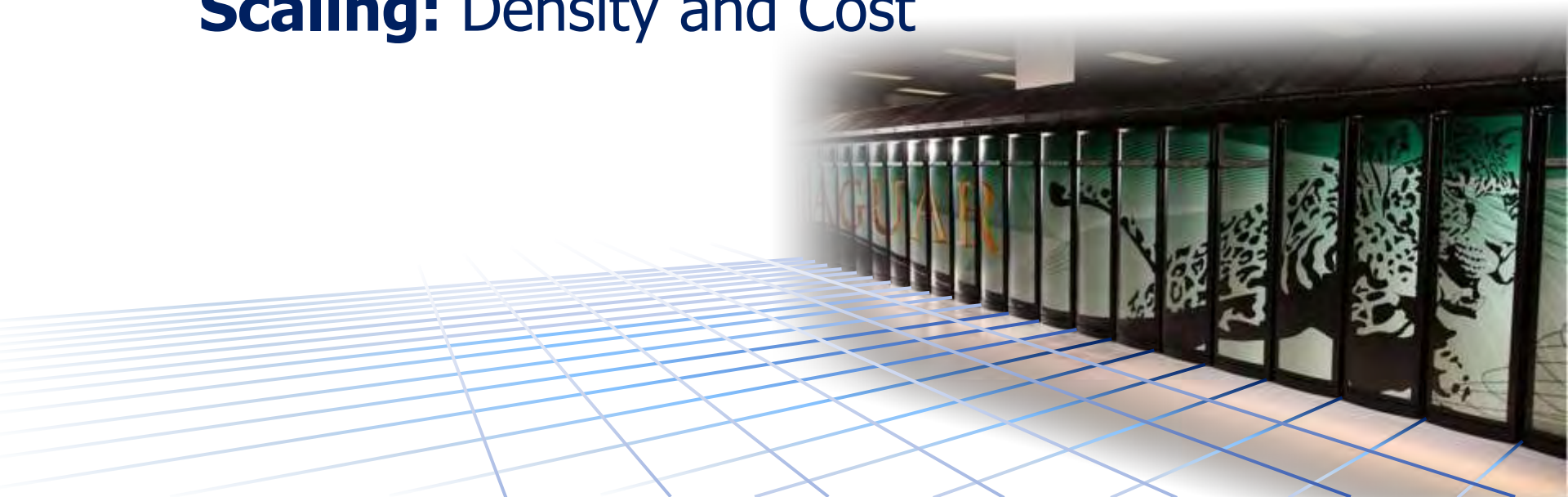
Issues with Storage (aka: Memory)

Performance: The Memory Wall

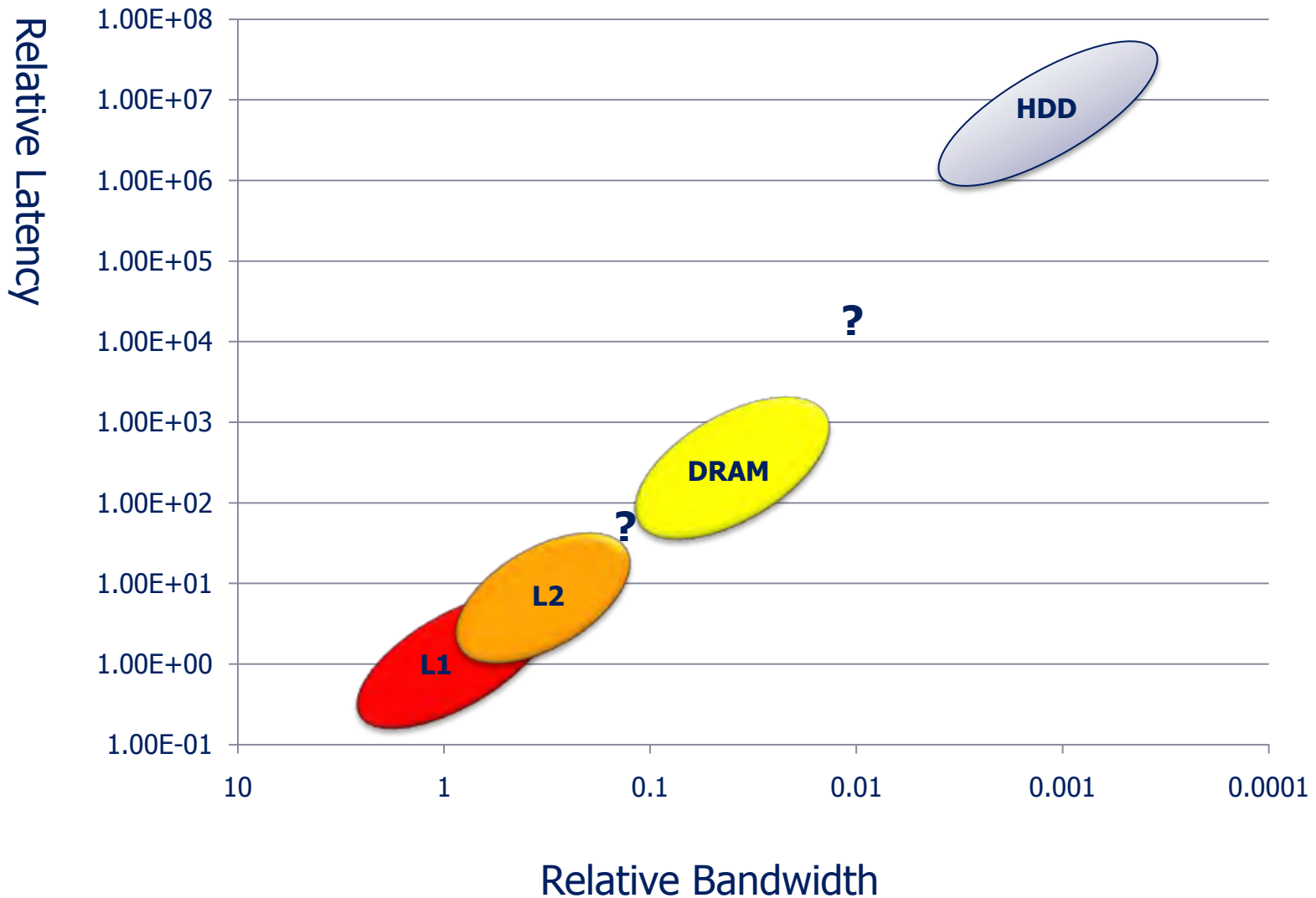
Power: Exabytes and Megawatts

Reliability: Redundancy and Resiliency

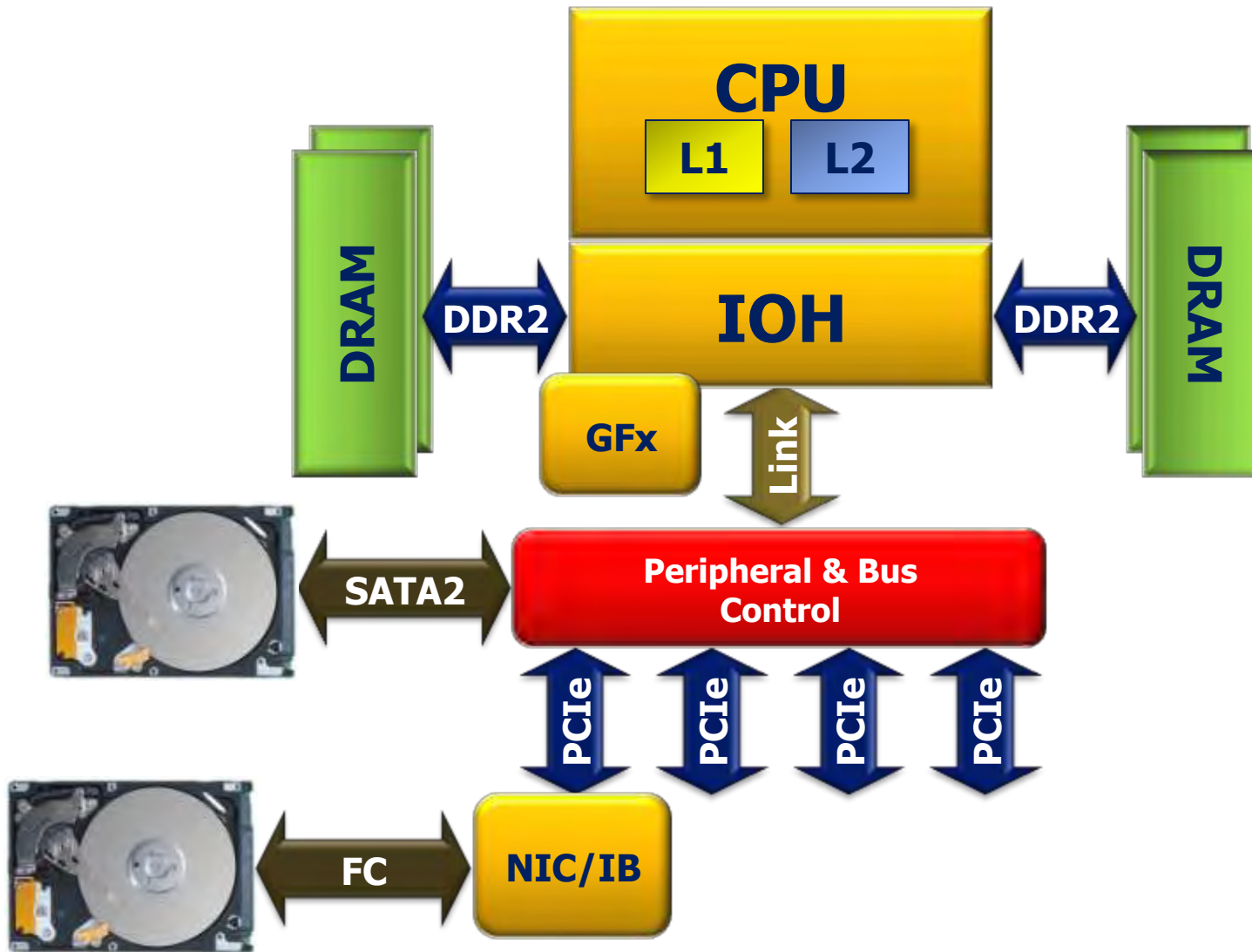
Scaling: Density and Cost



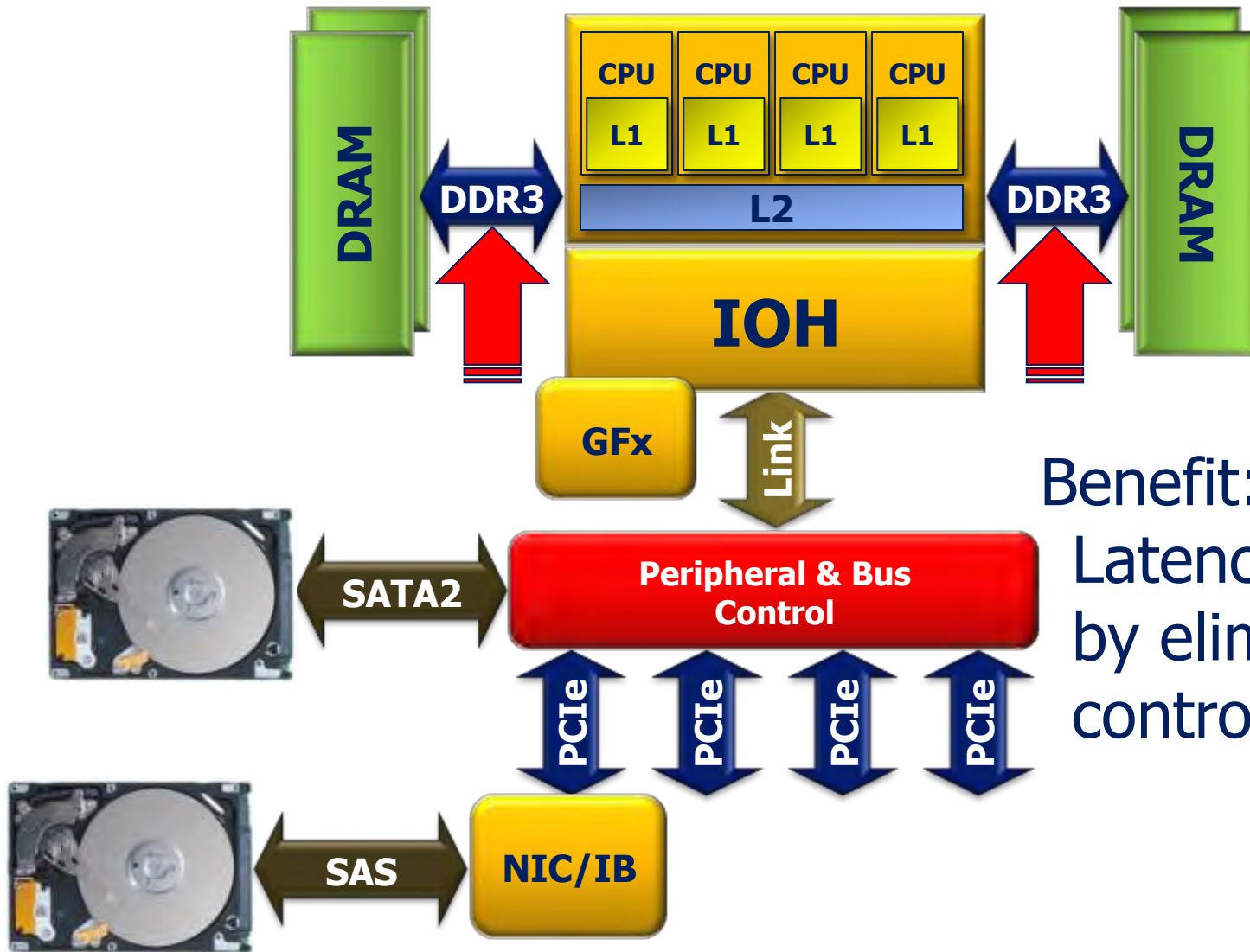
Memory Hierarchy Gaps



System Architecture



System Architecture



Benefit:
Latency reduction
by elimination of
controller "hops".

DDR4: Memory Architecture Improvement

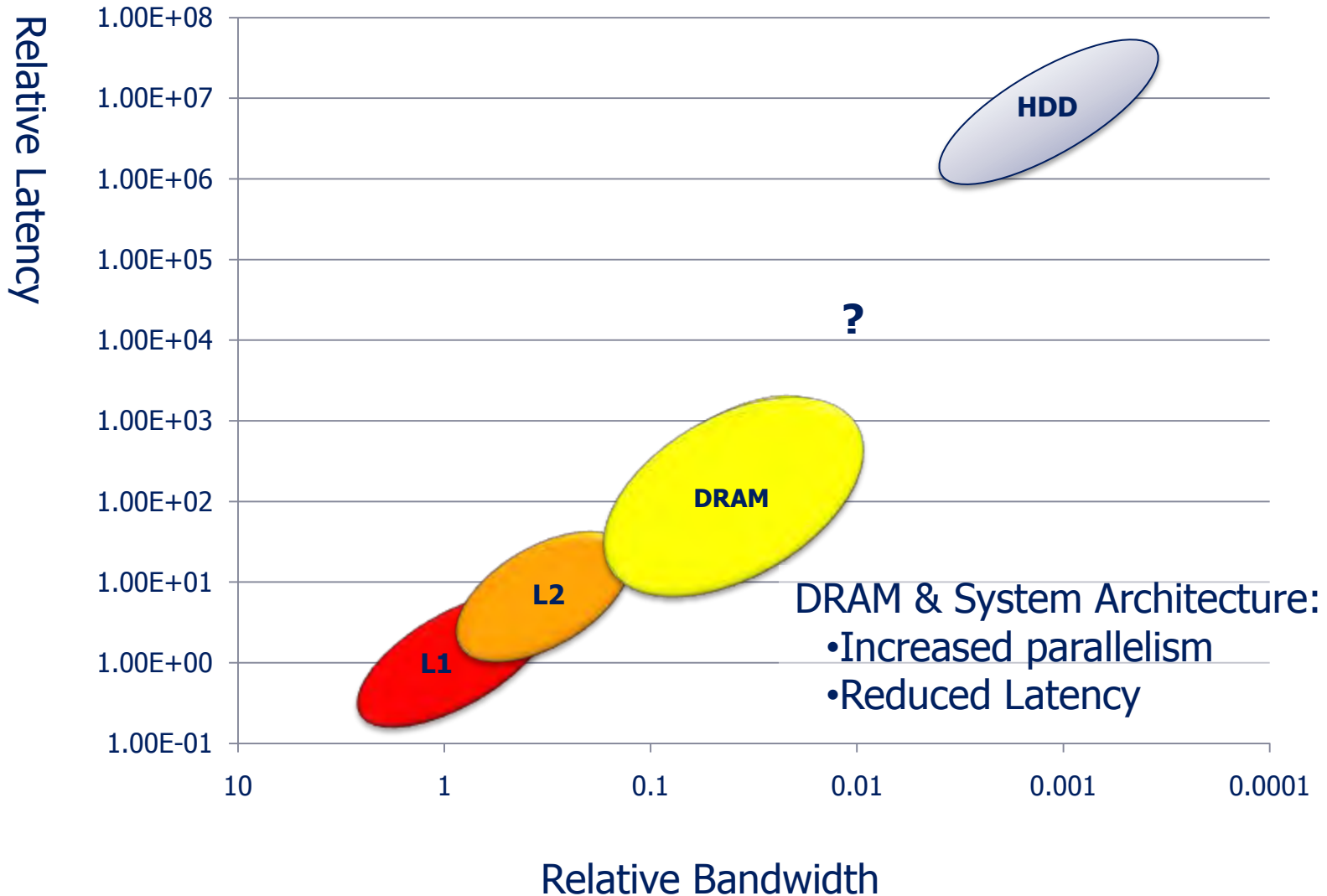
DDR4 is coming – High Bandwidth, Low Power, High Density

Major Advantages of DDR4:

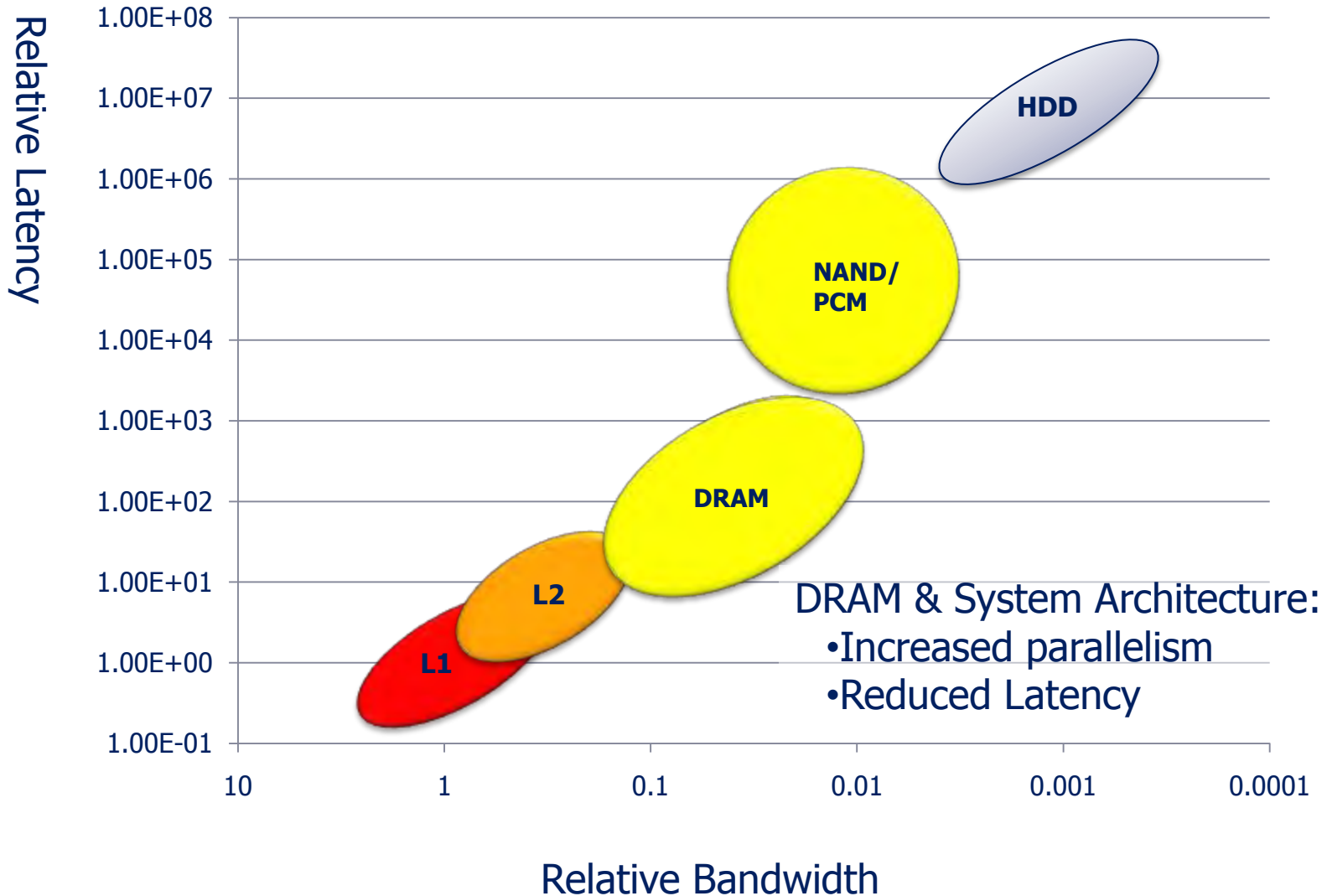
- High Bandwidth: **Up to 3.2 Gbps**
- Power Consumption: **1.2V** is 10-15% improvement over DDR3 & DDR3L
- High Density: 2Gb - 16Gb; **up to 8H** (128Gb stack); **single load**
- DDR4 **cost overhead** appears **better than** previous 1st gen technologies
- **Power, density and bandwidth:** Optimized for HPC and servers



Memory Hierarchy Gaps



Memory Hierarchy Gaps



Requirements

- Low random latency:
 - ▶ As the number of CPU cores (and thus the parallel tasks) increase the traffic becomes increasingly random.
 - ▶ As the use of VM's increase the traffic becomes increasingly random.
- High endurance:
 - ▶ Accepted DRAM endurance is $>1E15$ cycles.
 - ▶ Accepted NAND endurance is $<1E5$ cycles or $3E3$ cycles.
- Intelligent management

Closing the Storage to DRAM Gap

- Technical requirements:
 - ▶ Low latency
 - ▶ High endurance
 - ▶ Symmetric read and write
 - ▶ Block-based architecture
 - ▶ Able to use existing interfaces
- Economic requirements:
 - ▶ Lower cost/bit than DRAM
 - ▶ Lower power than DRAM

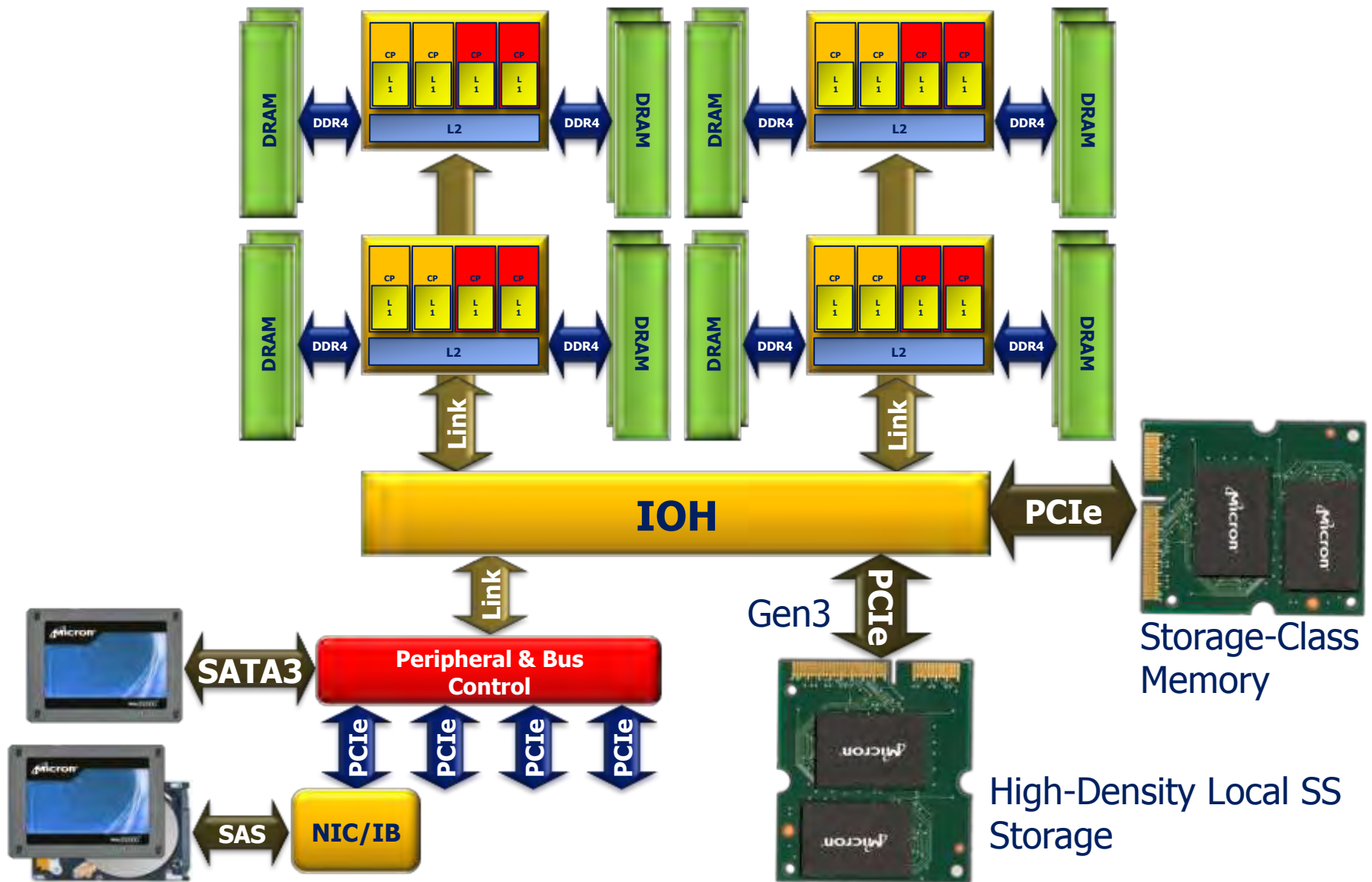
STEP 1:
SSD

STEP 2:
SCM

NAND Endurance

- NAND Process and Design
 - ▶ + Improved processes: new materials and structures
 - ▶ - Smaller geometries: fewer electrons and more interference
- SSD Architecture and Algorithms
 - ▶ + Improved error handling and efficiency
 - ▶ ++ NAND optimizations

Fast Forward: Future System Architecture



Solid State Storage as the Ultimate Cache

- Pinnable, secure, high performance.
- System software can:
 - ▶ Mitigate wear
 - ▶ Allow graceful degradation
 - ▶ Accelerate slower storage, both local and remote
- Fits with SSD today and PCM tomorrow.
- Can take advantage of lower latency, higher bandwidth connections.
- Optimized solution is integrated solution.

The Holistic Approach to Storage

- The gap between CPU and main memory is being closed by architecture and DRAM advanced.
- The gap between DRAM and storage is widening.
- Increasing randomization of storage traffic demands a storage system with low random latency.
- Endurance requirements will dictate advanced NAND management, and must include system software as a part of the solution.
- NAND, and ultimately PCM, will close the storage gap.



Focused on Memory | Engineered for Innovation